

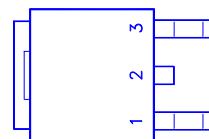
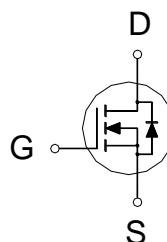
NIKO-SEM
**N-Channel Logic Level Enhancement
Mode Field Effect Transistor**
P1625ED

TO-252

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
250V	265m Ω	16A


 1.GATE
2.DRAIN
3.SOURCE
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	16	A
	$T_C = 100^\circ\text{C}$		10	
Pulsed Drain Current ¹		I_{DM}	47	
Avalanche Current		I_{AS}	8	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	32	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	83	W
	$T_C = 100^\circ\text{C}$		33	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	°C / W

¹Pulse width limited by maximum junction temperature.
ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	250			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	2.7	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 250\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 250\text{V}, V_{GS} = 0\text{V}, T_J = 55^\circ\text{C}$			10	

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Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 10V, I _D = 8A	211	265	mΩ
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 8A	14		S
DYNAMIC					
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 125V, f = 1MHz	752		pF
Output Capacitance	C _{oss}		61		
Reverse Transfer Capacitance	C _{rss}		12		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	5.9		Ω
Total Gate Charge ²	Q _g	V _{DS} = 125V, V _{GS} = 10V, I _D = 8A	20		nC
Gate-Source Charge ²	Q _{gs}		4.2		
Gate-Drain Charge ²	Q _{gd}		6.6		
Turn-On Delay Time ²	t _{d(on)}	V _{DD} = 125V I _D ≈ 8A, V _{GS} = 10V, R _{GEN} = 6Ω	22		nS
Rise Time ²	t _r		33		
Turn-Off Delay Time ²	t _{d(off)}		137		
Fall Time ²	t _f		53		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)					
Continuous Current	I _S			16	A
Forward Voltage ¹	V _{SD}	I _F = 16A, V _{GS} = 0V		1.2	V
Reverse Recovery Time	t _{rr}	I _F = 8A, dI _F /dt = 100A / μS	125		nS
Reverse Recovery Charge	Q _{rr}		573		nC

¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.²Independent of operating temperature.

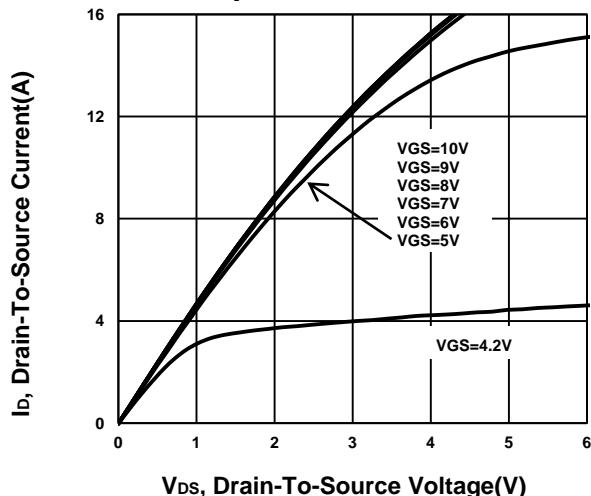
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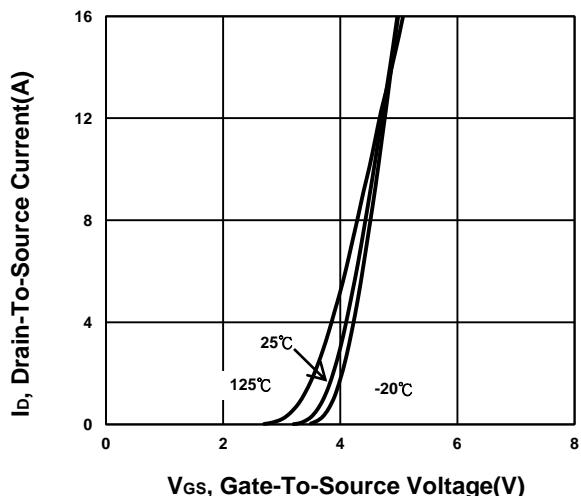
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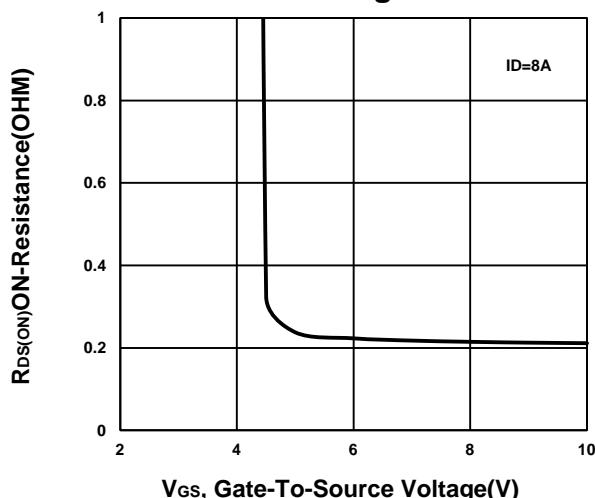
Output Characteristics



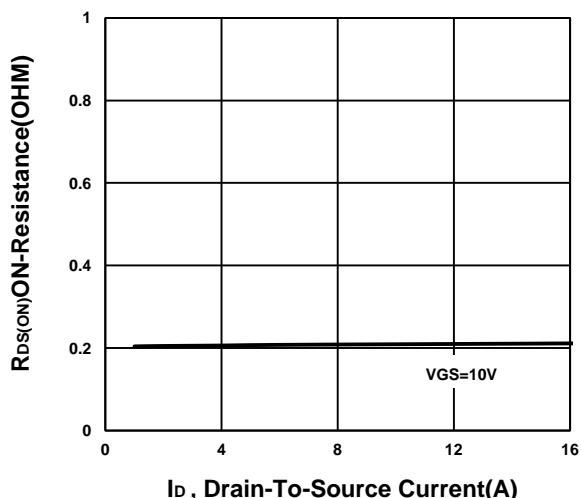
Transfer Characteristics



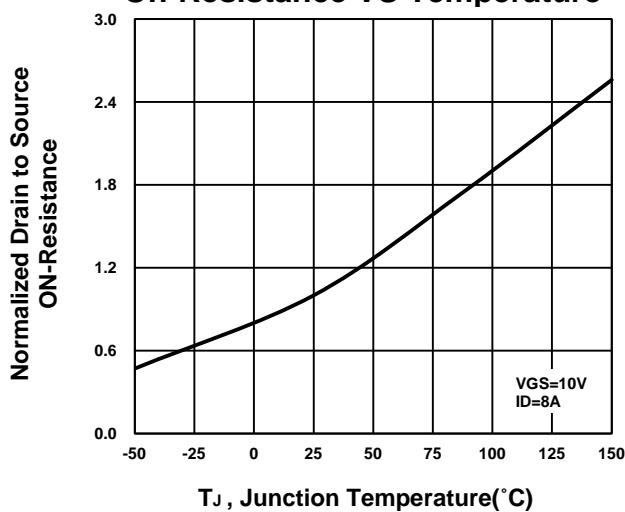
On-Resistance VS Gate-To-Source Voltage



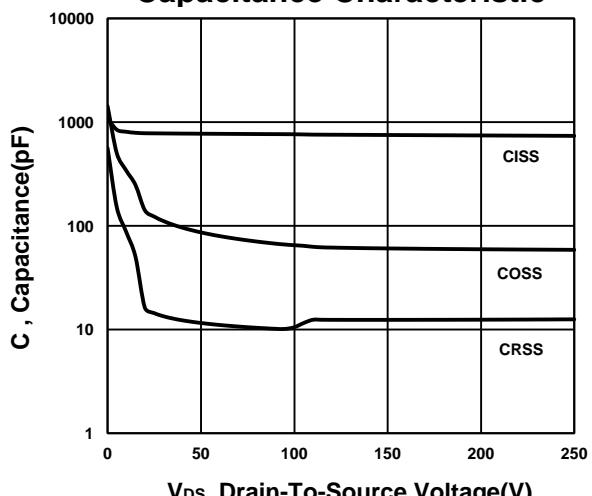
On-Resistance VS Drain Current



On-Resistance VS Temperature



Capacitance Characteristic



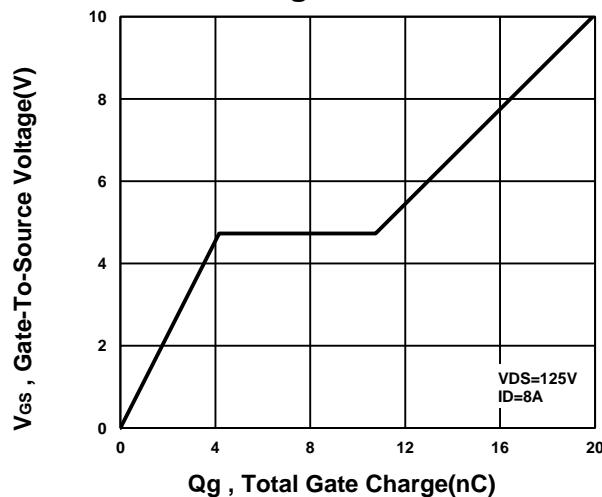
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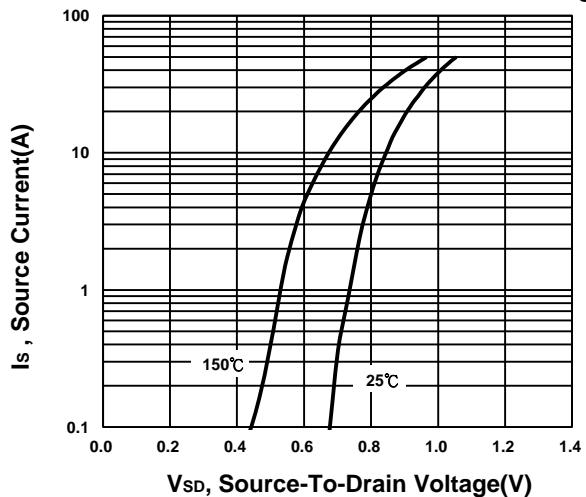
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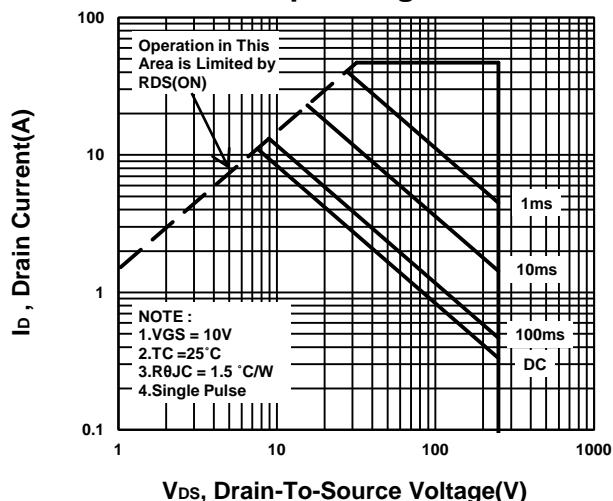
Gate charge Characteristics



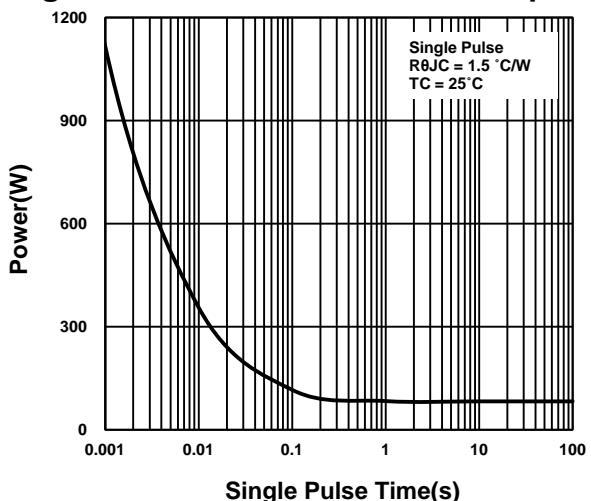
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

